

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an Additional Wafer Production Location GTBF Dongguan, China for TO220 and D2PAK 3L MOSFET Products.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19-April-2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Process / Product Change Notification



N° 1209-DISTI42-C4002348-Private

► **Products affected:**

Please refer to attached affected products list 1209-DISTI42-C4002348-AffectedParts.xlsx

► **Detailed Change Information:**

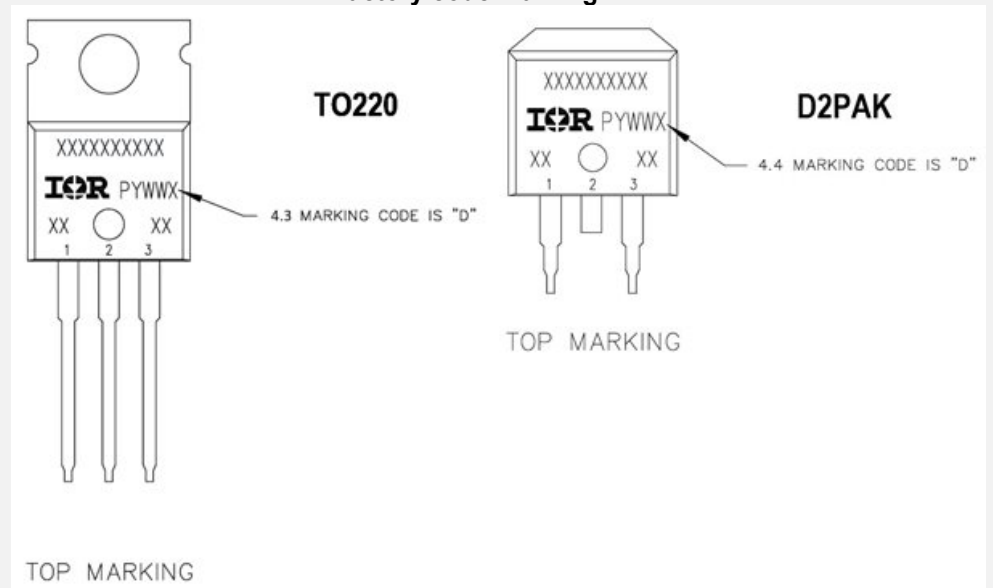
Subject: Introduction of an Additional Wafer Production Location GTBF Dongguan, China for TO220 and D2PAK 3L MOSFET Products.

Reason: Expansion of assembly production to assure continuity of supply and enable flexible manufacturing.

Description:

Old	New
<p>TO220</p> <ul style="list-style-type: none"> ▪ Assembly site SP Semiconductors, Korea ▪ Wire type Aluminum ▪ Mold compound SG-8200DL 	<p>SP Semiconductors, Korea and GTBF Dongguan, China</p> <p>NI-Doped Aluminum</p> <p>KE-G300BH</p>
<p>D2PAK</p> <ul style="list-style-type: none"> ▪ Assembly site SP Semiconductors, Korea ▪ Wire type Aluminum ▪ Mold compound SG-8300HDT 	<p>SP Semiconductors, Korea and GTBF Dongguan, China</p> <p>NI-DOPED AL WIRE</p> <p>CEL9220HF13MGP</p>

Factory code marking



Process / Product Change Notification



N° 1209-DISTI42-C4002348-Private

- **Product Identification:** Traceability assured via date code. Factory code marking is "D"(Section 4.3 for TO220 and Section 4.4 for D2Pak) at GTBF
- **Impact of Change:** No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function. The alternate assembly site will meet the same qualification level and POD specification as the existing assembly site.
- **Attachments:** 1209-DISTI42-C4002348-AffectedParts.xlsx
- **Time Schedule:**
- Final qualification report: Available on request
 - First samples available: Upon request
 - Intended start of delivery: 18-June-2019 or earlier upon customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 1209-DISTI42-C4002348-Private
Introduction of an additional assembly
production
GTBFDongguan, China for TO220
MOSFET Products



Sales Name	SP number	OPN	Package
IRFB38N20DPBF	SP001556010	IRFB38N20DPBF	TO220
IRFB52N15DPBF	SP001572332	IRFB52N15DPBF	TO220
IRF100B201	SP001561498	IRF100B201	TO220
IRF100S201	SP001550868	IRF100S201	D2PAK
IRF135B203	SP001576588	IRF135B203	TO220
IRF135S203	SP001570032	IRF135S203	D2PAK